



PRODUCTS | APPLICATIONS | DESIGN SUPPORT | TRAINING | SAMPLE AND BUY | ABOUT US | CONTACT US | myMicrochip Login

# Product Change Notification - JAON-29FMVF751

Date:28 Jun 2016Product Category:Supertex

Notification subject: CCB 2513 Final Notice: Qualification of GTK assembly site for selected Supertex products using

wafers with non-Au backside coating available in 3L TO-92 package.

Notification text: PCN Status: Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** 

Qualification of GTK assembly site for selected Supertex products using wafers with non-Au backside coating available in 3L TO-92 package.

Pre Change:

Assembled at CRTK assembly site

Post Change:

Assembled at GTK assembly site

# Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	CRTK assembly site	GTK assembly site
Wire material	Au wire	Au wire
Die attach material	84-1 LMISR4	CRM-1076DJ-G
Molding compound material	G600	G600
Lead frame material	KFC	A194
Die Thickness	11 mil	8 mil

# Impacts to Data Sheet:

None

Reason for Change:

To improve productivity by qualifying GTK assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 20, 2016 (date code: 1629)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

#### Time Table Summary:

	June 2016				July 2016				
Workweek	22	23	24	25	26	27	28	29	30
Initial PCN Issue Date		Х							
Qual Report Availability					Х				
Final PCN Issue Date					Χ				
Estimated Implementation Date								X	

# Markings to Distinguish Revised from Unrevised Devices:

Traceability code

### **Revision History:**

June 8, 2016: Issued initial notification.

June 28, 2016: Issued final notification. Attached the qualification report. Provided estimated first ship date.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): PCN\_JAON-29FMVF751\_Qual\_Report.pdf

PCN\_JAON-29FMVF751\_Affected\_CPN.pdf PCN\_JAON-29FMVF751\_Affected\_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to change your product/process change notification (PCN) profile please log on to our website at <a href="http://www.microchip.com/PCN">http://www.microchip.com/PCN</a> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."













Products | Applications | Design Support | Training | Sample and Buy | About Us | Contact Us | Legal | Investors | Careers | Support

©Copyright 1998-2016 Microchip Technology Inc. All rights reserved. Shanghai ICP Recordal No.09049794 JAON-29FMVF751 - CCB 2513 Final Notice: Qualification of GTK assembly site for selected Supertex products using wafers with non-Au backside coating available in 3L TO-92 package.

Affected Catalog Part Numbers (CPN)

PCN_JAON-29FMVF751				
CATALOG_PART_NBR				
CL25N3-G				
CL2N3-G				
CL2N3-G-D591				
CL2N3-G-D602				
CL2N3-G-P002				
CL520N3-G				
CL525N3-G				
LND150N3-G				
LND150N3-G-P002				
LND150N3-G-P003				
LND150N3-G-P013				
LND150N3-G-P014				
LP0701N3-G				